

CALL FOR PAPERS

IEEE INTERNATIONAL INTEGRATED RELIABILITY WORKSHOP

IIRW

IEEE

INTERNATIONAL INTEGRATED
RELIABILITY WORKSHOP

October 13-17, 2019

**Stanford Sierra
Conference Center
Fallen Leaf Lake,
CA, USA**

Abstract Deadline
July 16, 2019

Late News Deadline
August 31, 2019

General Chair:
Zakariae Chbili
Intel, USA

TPC Chair:
Stanislav Tyaginov
imec, Belgium

www.iirw.org

The **IEEE International Integrated Reliability Workshop (IIRW)** focuses on ensuring electronic device reliability through fabrication, design, testing, characterization, and simulation, as well as identification of the defects and physical mechanisms responsible for reliability problems.

IIRW 2019

- Reliability Experts Forum: 1-day long discussion among the top reliability experts to discuss the current understanding and challenges in Emerging Memory Reliability physics. Several Panel discussions.
- Best student Paper award
- Top 5 papers will be published in IEEE TDMR

Outstanding features of the IIRW are

- Strong plenary, invited, and tutorial presentations
- Strong technical program (platform and posters)
- Unparalleled opportunities to meet world-leading experts
- Discussion and special interest groups
- Unique rustic and secluded environment

IIRW 2019 invites abstracts related to the reliability of

- Gate/Interconnect dielectrics (high- k , SiO₂, SiON, low- k)
- Conventional and emerging memory devices (RRAM, etc.)
- FinFET, SOI, FDSOI, non-CMOS (III-V), and novel devices
- Emerging technologies and devices (2D materials, IGZO, etc)
- Power and wide bandgap (SiC, GaN, etc.) device reliability.
- Transistor reliability (hot carriers, NBTI/PBTI, TDDB)
- Modeling and simulation of reliability issues
- Impact of transistor degradation on circuit reliability
- Design-in reliability (products, circuits, systems, processes)
- Customer/manufacturer product reliability requirements
- Wafer level reliability tests

Two page abstract with representative data and figures should state clearly the results of your work and why they are significant.

**For more information please visit www.iirw.org, or contact the technical program chair:
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